

Specification

RESIN-HAVING METAL FOIL FOR MULTILAYERED WIRING BOARD, PROCESS FOR PRODUCING THE SAME, MULTILAYERED WIRING BOARD, AND ELECTRONIC DEVICE

Technical Field

This invention relates to metal foil having provided on one side thereof a thermosetting resin film which is for use in a multilayered wiring board, a process for producing the resin-having metal foil, a multilayered wiring board having the resin-having metal foil, and an electronic device having an electronic component electrically connected to the multilayered wiring board. The multilayered wiring board according to the present invention has practically the same distance between wiring layers irrespective of the in-plane positions of the multilayered wiring board, showing small variation in characteristic impedance. Therefore, it exhibits very excellent characteristics as a wiring board for ultrahigh-speed digital circuits. The electronic device according to the present invention has excellent stability of the characteristic impedance and, with a digital semiconductor mounted as an electronic element, allows the digital semiconductor to operate at a higher speed and, with a semiconductor having an analog portion mounted as an electronic element, can handle signals of higher frequency because crosstalks of the signals are reduced. Where a resin having a glass transition temperature of 180°C or higher after heat curing is used, the multilayered wiring board and